



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
	<b>Manufacturing Info</b>		<b>* : Required Field</b>


Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>17-02-2022</b>
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Material Declaration champion</b>	<b>Representative Title</b>	<b>Material Declaration champion</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H742VIT6 STM32H742VIT6TR	P31L*450XXXV	A	9998	17-02-2022
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH - 8th July 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	P31L*450XXV				7000001.0	1000004.0				
note : Substance present with less 0.001mg will not be declared in this document																
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die - or dies	M-011 Other inorganic materials	15.700	mg	supplier	die	Silicon (Si)	7440-21-3		14.958	mg	952739	21951				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5605	129				
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	17580	405				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	64	1				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2866	66				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	510	12				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	64	1				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	20573	474				
				Leadframe (Mht - C194)	Copper and its alloy	133.067	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		129.740	mg	975000	190391
								supplier	ALLOY	Iron (Fe)	7439-89-6		3.127	mg	23500	4589
supplier	ALLOY	Zinc (Zn)	7440-66-6						0.160	mg	1200	234				
supplier	ALLOY	Metallic Phosphorus (P)	7723-14-0						0.040	mg	300	59				
supplier	COATING	Silver (Ag)	7440-22-4						5.101	mg	1000000	7486				
Leadframe Plating (Mht - Ag)	M-011 Other inorganic materials	5.101	mg	supplier	COATING	Silver (Ag)	7440-22-4		5.101	mg	1000000	7486				
Glue (evertech - ap4200)	M-011 Other inorganic materials	1.033	mg	supplier	GLUE	Formaldehyde, oligomeric reaction products w	9003-36-5		0.165	mg	160000	243				
				supplier	GLUE	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8		0.015	mg	15000	23				
				supplier	GLUE	Formaldehyde, oligomeric reaction products w	9003-35-4		0.015	mg	15000	23				
				supplier	GLUE	2-butoxyethyl acetate	112-07-2		0.041	mg	40000	61				
				supplier	GLUE	Silver	7440-22-4		0.795	mg	770000	1167				
Bonding Wire (Mke - Au Wire Hts 2N)	M-011 Other inorganic materials	2.951	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.921	mg	990000	4287				
				supplier	BONDING WIRE	Others	Proprietary		0.030	mg	10000	43				
Encapsulation (Sumitomo - G631Sh T)	M-011 Other inorganic materials	520.322	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		5.203	mg	10000	7636				
				supplier	MOLDING COMPOUND	Epoxy Resin B	Proprietary		5.203	mg	10000	7636				
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		26.016	mg	50000	38178				
				supplier	MOLDING COMPOUND	Silica(Amorphous) A	60676-86-0		408.453	mg	785000	599397				
				supplier	MOLDING COMPOUND	Silica(Amorphous) B	7631-86-9		72.845	mg	140000	106899				
Finishing (Sytron- Matte Sn Plating)	M-011 Other inorganic materials	3.269	mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		2.602	mg	5000	3818				
				supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		3.269	mg	1000000	4797				